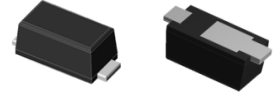


## Features

- Heatsink structure
- Low profile, typical thickness 0.8mm
- Low leakage current
- Super Low VF Schottky barrier diodes
- Moisture sensitivity: level 1, per J-STD-020
- High temperature soldering guaranteed: 260°C/10 seconds



Package: iSGA  
(SOD-123HS)

## Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	GPL26	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	60	V
Maximum RMS voltage	$V_{RMS}$	42	V
Maximum DC blocking voltage	$V_{DC}$	60	V
Maximum average forward rectified current	$I_{F(AV)}$	2.0	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	50	A
Operating junction temperature range	$T_J$	- 55 to + 125	$^\circ\text{C}$
Storage temperature range	$T_{STG}$	- 55 to + 150	$^\circ\text{C}$

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	GPL26	Unit
Maximum instantaneous forward voltage	$I_F=1\text{A}, T_A=25^\circ\text{C}$	$V_F$	0.45	V
	$I_F=2\text{A}, T_A=25^\circ\text{C}$		0.50	
Maximum DC reverse current at rated DC blocking voltage	$T_A=25^\circ\text{C}$	$I_R$	200	$\mu\text{A}$
	$T_A=125^\circ\text{C}$		100	mA
Typical junction capacitance	4.0 V, 1 MHz	$C_J$	125	pF
Typical thermal resistance <sup>1)</sup>	junction to ambient	$R_{\theta JA}$	85	$^\circ\text{C}/\text{W}$
	junction to mount	$R_{\theta JM}$	30	

Note:1),The thermal resistance from junction to ambient,case or mount,mounted on P.C.B with 5×5mm copper pads,2 OZ,FR4 PCB

**Typical Electrical Characteristic Curves**

( $T_A=25^\circ\text{C}$  unless otherwise noted)

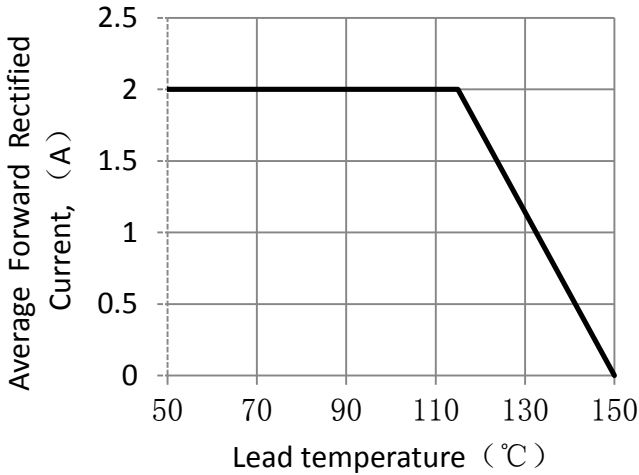


Figure 1. Forward Current Derating Curve

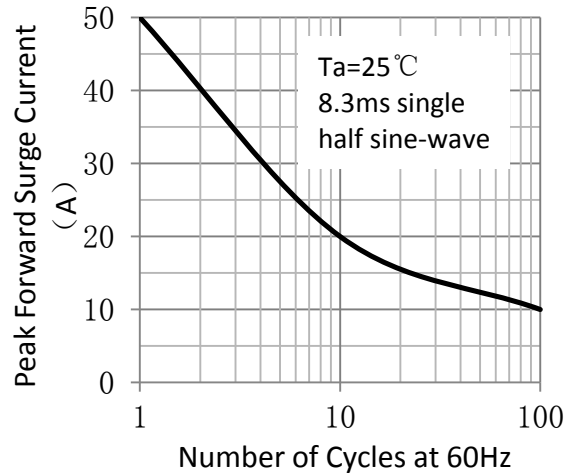


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

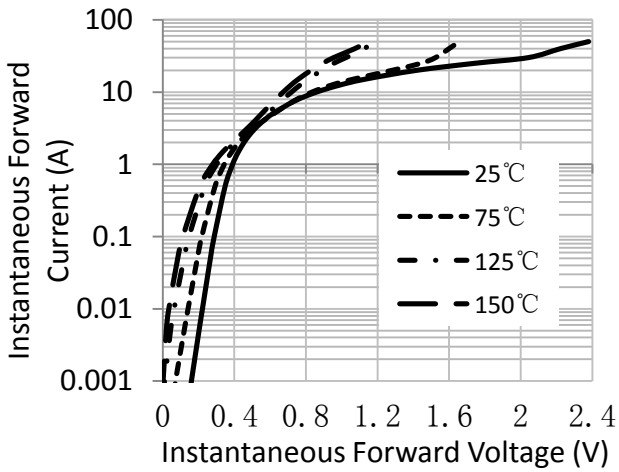


Figure 3. Typical Instantaneous Forward Characteristics

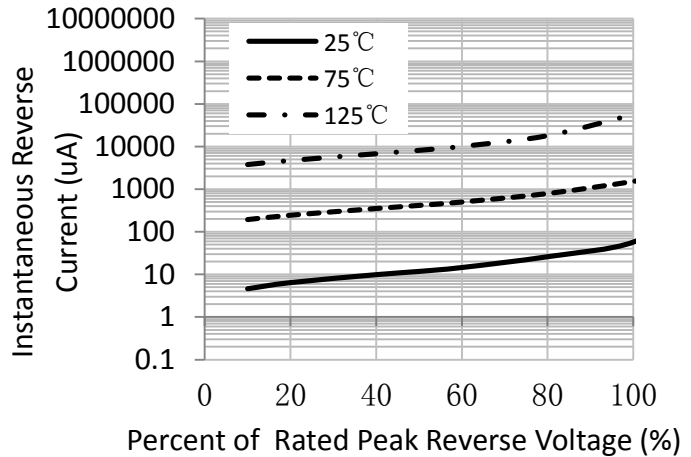


Figure 4. Typical Reverse Characteristics

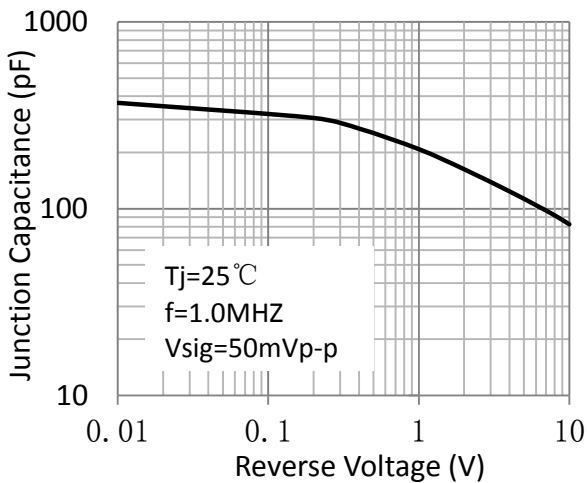
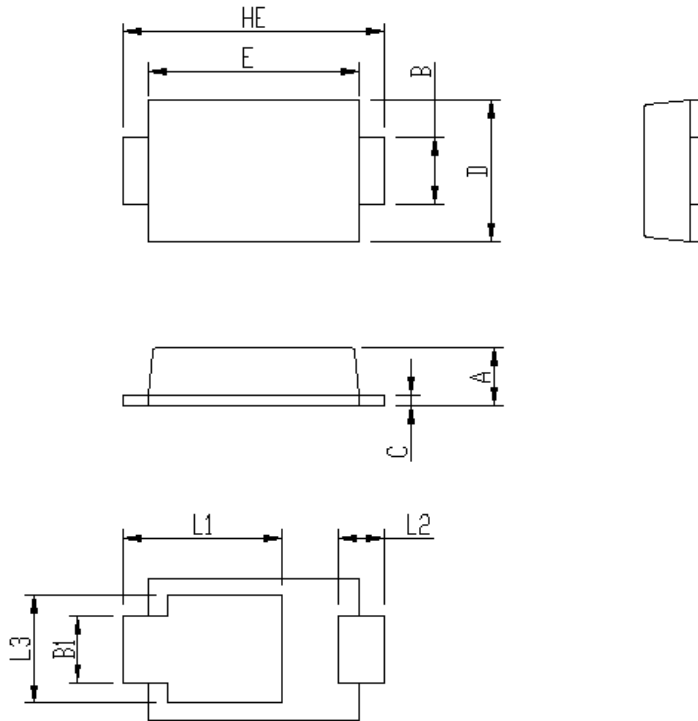


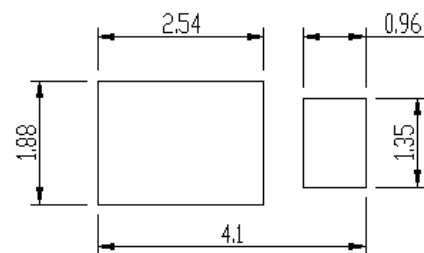
Figure 5. Typical Junction Capacitance

## Package Outline Dimensions



Package	iSGA	
Unit:mm	MIN	MAX
A	0.75	0.90
B	0.85	1.05
B1	0.85	1.05
C	0.1	0.25
D	1.9	2.1
E	2.9	3.1
L1	2.0	2.45
L2	0.4	0.85
L3	1.3	1.7
HE	3.5	3.9

### Soldering footprint



## Packing Information

### Packing Quantities

Reel size	Quantity/reel	Quantity/inner Box	Quantity/Carton
7"	3K	30K	120K

### Tape & Reel Specification

